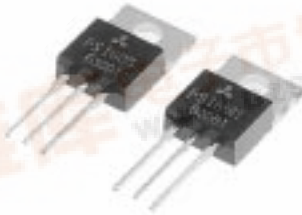


MITSUBISHI Nch POWER MOSFET

FS16UM-6

HIGH-SPEED SWITCHING USE

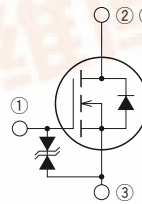
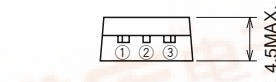
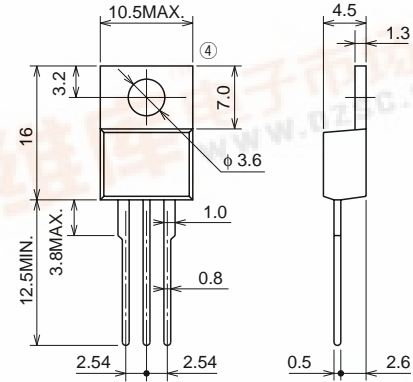
FS16UM-6



- V_{DSS} 300V
- $r_{DS(ON)}$ (MAX) 0.33Ω
- I_D 16A

OUTLINE DRAWING

Dimensions in mm



- ① GATE
- ② DRAIN
- ③ SOURCE
- ④ DRAIN

TO-220

APPLICATION

SMPS, DC-DC Converter, battery charger, power supply of printer, copier, HDD, FDD, TV, VCR, personal computer etc.

MAXIMUM RATINGS (Tc = 25°C)

Symbol	Parameter	Conditions	Ratings	Unit
V_{DSS}	Drain-source voltage	$V_{GS} = 0V$	300	V
V_{GSS}	Gate-source voltage	$V_{DS} = 0V$	± 30	V
I_D	Drain current		16	A
I_{DM}	Drain current (Pulsed)		48	A
P_D	Maximum power dissipation		125	W
T_{ch}	Channel temperature		-55 ~ +150	°C
T_{stg}	Storage temperature		-55 ~ +150	°C
—	Weight	Typical value	2.0	g

FS16UM-6

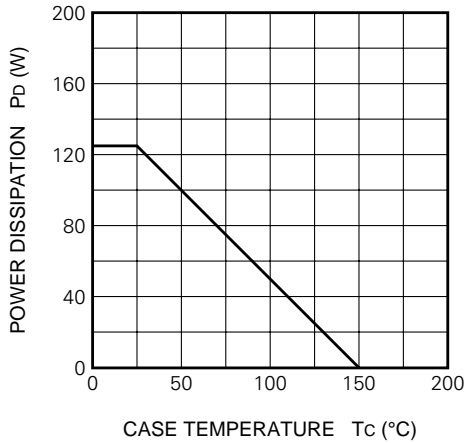
HIGH-SPEED SWITCHING USE

ELECTRICAL CHARACTERISTICS (T_{ch} = 25°C)

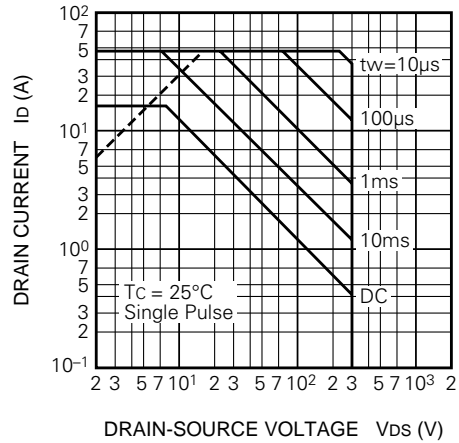
Symbol	Parameter	Test conditions	Limits			Unit
			Min.	Typ.	Max.	
V (BR) DSS	Drain-source breakdown voltage	I _D = 1mA, V _{GS} = 0V	300	—	—	V
V (BR) GSS	Gate-source breakdown voltage	I _G = ±100μA, V _{DS} = 0V	±30	—	—	V
I _{GSS}	Gate-source leakage current	V _{GS} = ±25V, V _{DS} = 0V	—	—	±10	μA
I _{DSS}	Drain-source leakage current	V _{DS} = 300V, V _{GS} = 0V	—	—	1	mA
V _{GS} (th)	Gate-source threshold voltage	I _D = 1mA, V _{DS} = 10V	2	3	4	V
r _{DS} (ON)	Drain-source on-state resistance	I _D = 8A, V _{GS} = 10V	—	0.25	0.33	Ω
V _{DS} (ON)	Drain-source on-state voltage	I _D = 8A, V _{GS} = 10V	—	2.0	2.64	V
y _{fs}	Forward transfer admittance	I _D = 8A, V _{DS} = 10V	6.5	10.0	—	S
C _{iss}	Input capacitance	V _{DS} = 25V, V _{GS} = 0V, f = 1MHz	—	1050	—	pF
C _{oss}	Output capacitance		—	220	—	pF
C _{rss}	Reverse transfer capacitance		—	45	—	pF
t _d (on)	Turn-on delay time	V _{DD} = 150V, I _D = 8A, V _{GS} = 10V, R _{GEN} = R _{GS} = 50Ω	—	20	—	ns
t _r	Rise time		—	40	—	ns
t _d (off)	Turn-off delay time		—	110	—	ns
t _f	Fall time		—	50	—	ns
V _{SD}	Source-drain voltage		I _S = 8A, V _{GS} = 0V	—	1.5	2.0
R _{th} (ch-c)	Thermal resistance	Channel to case	—	—	1.00	°C/W

PERFORMANCE CURVES

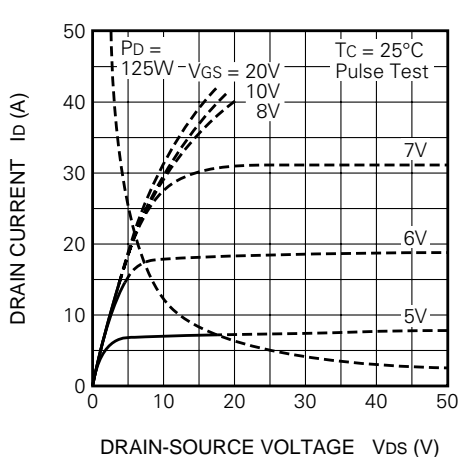
POWER DISSIPATION DERATING CURVE



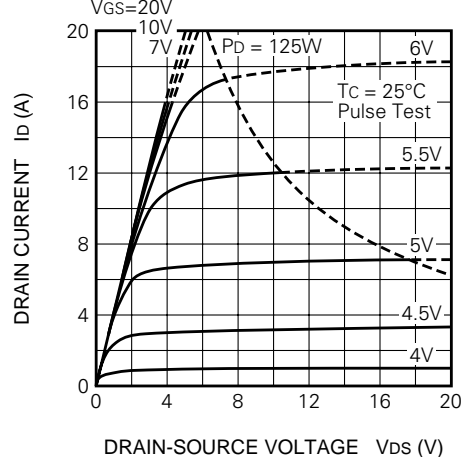
MAXIMUM SAFE OPERATING AREA



OUTPUT CHARACTERISTICS (TYPICAL)



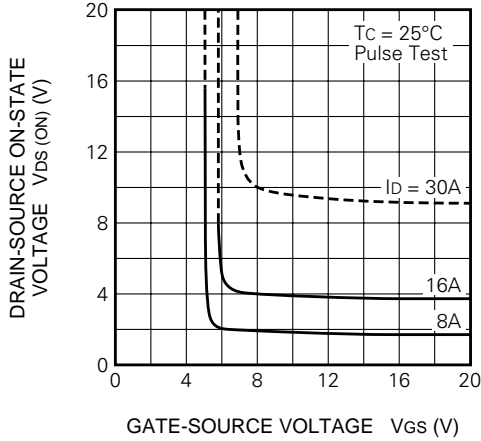
OUTPUT CHARACTERISTICS (TYPICAL)



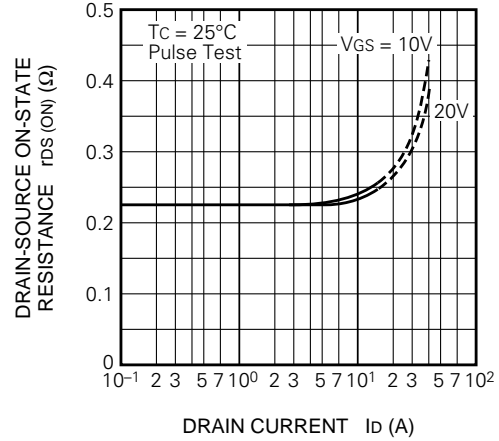
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HIGH-SPEED SWITCHING USE

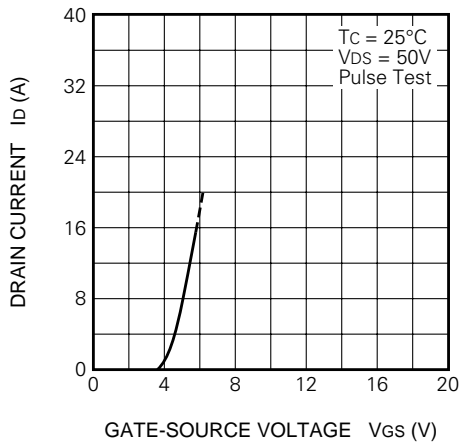
ON-STATE VOLTAGE VS. GATE-SOURCE VOLTAGE (TYPICAL)



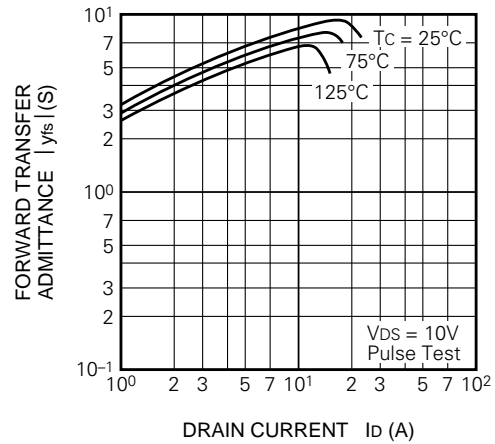
ON-STATE RESISTANCE VS. DRAIN CURRENT (TYPICAL)



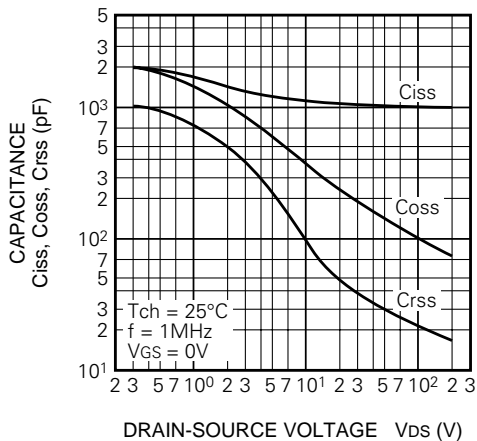
TRANSFER CHARACTERISTICS (TYPICAL)



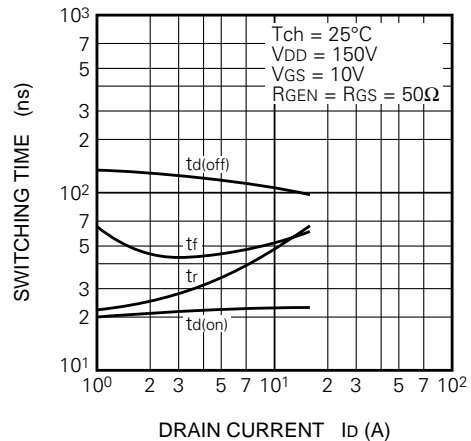
FORWARD TRANSFER ADMITTANCE VS. DRAIN CURRENT (TYPICAL)



CAPACITANCE VS. DRAIN-SOURCE VOLTAGE (TYPICAL)



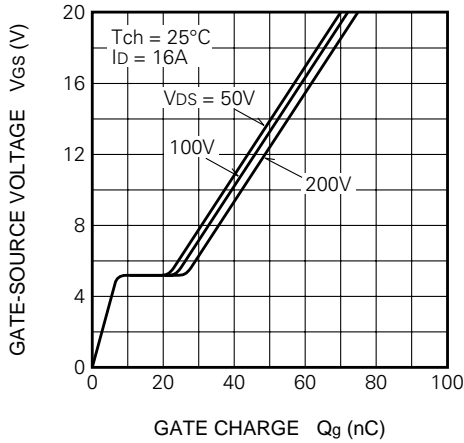
SWITCHING CHARACTERISTICS (TYPICAL)



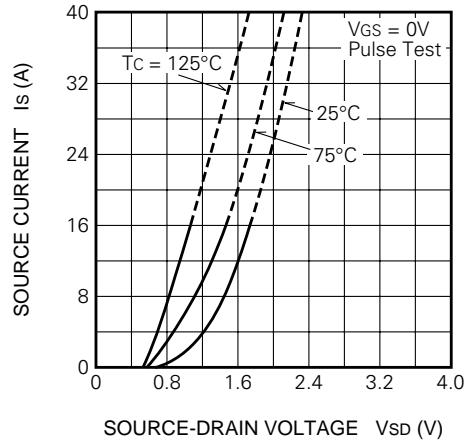
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HIGH-SPEED SWITCHING USE

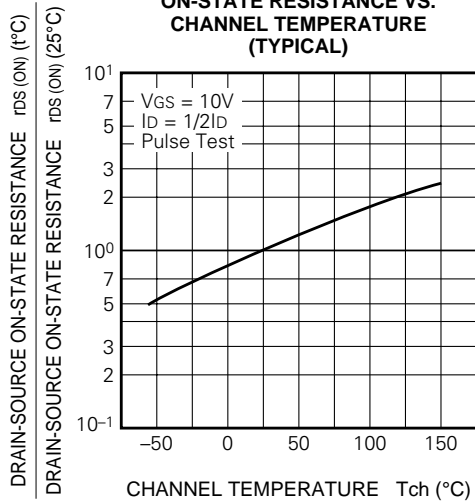
GATE-SOURCE VOLTAGE VS. GATE CHARGE (TYPICAL)



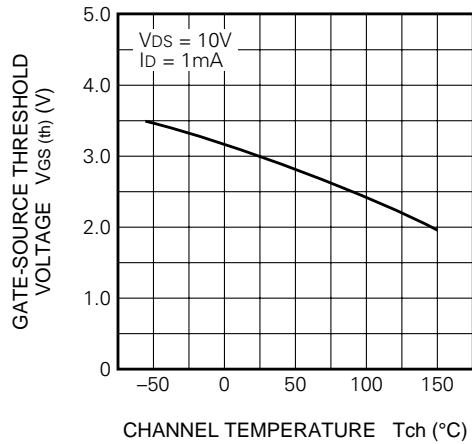
SOURCE-DRAIN DIODE FORWARD CHARACTERISTICS (TYPICAL)



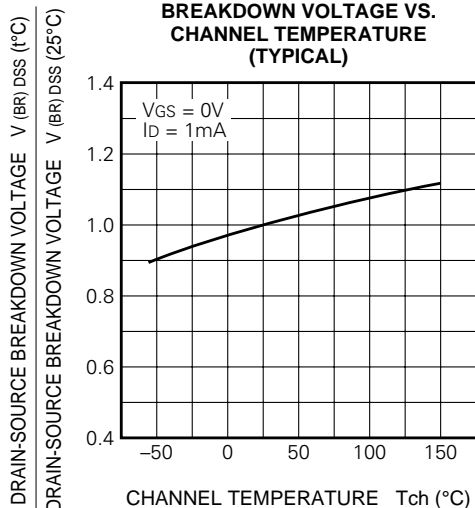
ON-STATE RESISTANCE VS. CHANNEL TEMPERATURE (TYPICAL)



THRESHOLD VOLTAGE VS. CHANNEL TEMPERATURE (TYPICAL)



BREAKDOWN VOLTAGE VS. CHANNEL TEMPERATURE (TYPICAL)



TRANSIENT THERMAL IMPEDANCE CHARACTERISTICS

